

PCN Number:	20201210002.1		PCN Date:	Dec 18, 2020	
Title:	Qualification of additional Fab site (DMOS6) and additional Assembly site (CARZ) for select LBC9 devices				
Customer Contact:	PCN Manager		Dept:	Quality Services	
Proposed 1st Ship Date:	Mar 18, 2021		Estimated Sample Availability:	Date provided at sample request.	
Change Type:					
<input checked="" type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Assembly Materials
<input type="checkbox"/>	Design	<input type="checkbox"/>	Electrical Specification	<input type="checkbox"/>	Mechanical Specification
<input type="checkbox"/>	Test Site	<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
<input type="checkbox"/>	Wafer Bump Site	<input type="checkbox"/>	Wafer Bump Material	<input type="checkbox"/>	Wafer Bump Process
<input checked="" type="checkbox"/>	Wafer Fab Site	<input type="checkbox"/>	Wafer Fab Materials	<input type="checkbox"/>	Wafer Fab Process
		<input type="checkbox"/>	Part number change		
PCN Details					
Description of Change:					
Texas Instruments is pleased to announce the qualification of an additional fab (DMOS6) and assembly site (CARZ) for selected devices as listed below in the product affected section.					
Current Site			Additional Site		
Current Fab Site	Process	Wafer Diameter	Additional Fab Site	Process	Wafer Diameter
RFAB	LBC9	300 mm	DMOS6	LBC9	300 mm
Construction differences are as follows:					
		CDAT Current	CARZ New		
	Mount Compound	4207123	435143		
	Mold Compound	4222198	441086		
	Lead finish	NiPdAu	NiPdAuAg		
Reason for Change:					
Continuity of Supply					
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):					
None					
Anticipated impact on Material Declaration					
<input type="checkbox"/>	No Impact to the Material Declaration	<input checked="" type="checkbox"/>	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI ECO website .		
Changes to product identification resulting from this PCN:					
Fab Site Information:					
Chip Site	Chip Site Origin Code (20L)	Chip Site Country Code (21L)	Chip Site City		
RFAB	RFB	USA	Richardson		
DMOS6	DM6	USA	Dallas		
Assembly Site Information:					
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City		
CDAT	CDA	CHN	Chengdu		
CARZ	CSZ	CHN	Jiangsu		

Sample product shipping label (not actual product label)



MADE IN: Malaysia
2DC: 20:



MSL 2 / 260C / 1 YEAR	SEAL DT
MSL 1 / 235C / UNLIM	03/29/04

OPT: 39
ITEM: LBL: 5A (L) TO: 1750

(1P) SN74LS07NSR
(Q) 2000 (D) 0336
(31T) LOT: 3959047MLA
(4W) TKY (1T) 7523483SI2
(P)
(2P) REV: (V) 0053817
(20L) CSO: SHE (21L) CCO: USA
(22L) ASO: MLA (23L) ACO: MYS

Product Affected:

LP5018RSMR	LP5024RSMR
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Qualification Report

Approve Date 02-Dec-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LP5018RSMR	QBS Process Reference: TLV62569DBVR	QBS Package Reference: LMR33630CQRNXRQ1
AC	Autoclave, 121C	96 Hours	-	3/231/0	-
ED	Electrical Characterization	Per Datasheet Parameters	1/30/0	3/90/0	3/90/0
ELFR	Early Life Failure Rate, 125C	48 Hours	-	3/2400/0	3/2400/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	3/231/0	-
HAST	Biased HAST, 110C/85%RH	264 Hours	-	-	3/231/0
HBM	ESD - HBM	4000 V	1/3/0	-	-
CDM	ESD - CDM	1500 V	1/3/0	-	-
HBM	ESD - HBM	2000 V	-	3/9/0	3/9/0
CDM	ESD - CDM	500 V	-	3/9/0	3/9/0
HTOL	Life Test, 125C	1000 Hours	-	3/231/0	3/231/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	-	3/231/0	3/231/0
LU	Latch-up	(per JESD78)	1/6/0	1/6/0	318/0
SD	Solderability	Pb Free	-	-	1/30/0
TC	Temperature Cycle, -65/150C	500 Cycles	-	3/231/0	3/231/0
UHAST	Unbiased HAST, 130C/85%RH	96 Hours	-	-	-
UHAST	Unbiased HAST, 110C/85%RH	264 Hours	-	-	3/231/0

- QBS: Qual By Similarity

- Qual Device LP5018RSMR is qualified at LEVEL2-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours

- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/>

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

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